

L Number	Hits	Search Text	DB	Time stamp
-	2	("5046238").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/09/02 13:18
-	72	5046238.URPN.	USPAT	2004/09/02 13:20
-	2	("5401913").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/09/02 13:41
-	5	("4238527" "4554033" "4576670" "4925723" "5046238").PN.	USPAT	2004/09/02 13:43
-	19	5601678.URPN.	USPAT	2004/09/02 13:43
-	25	5401913.URPN.	USPAT	2004/09/02 13:46
-	9	("5291062" "5309629" "5367435" "5457881" "5601678" "5764485" "5879787" "5888627" "6037044").PN.	USPAT	2004/09/02 13:48
-	16	("3835531" "3948706" "3953924" "4075757" "4634631" "4647508" "4788766" "4818728" "4849284" "4864722" "4868350" "4874721" "4902606" "5030499" "5046238" "5192775").PN.	USPAT	2004/09/02 13:49
-	17	5309629.URPN.	USPAT	2004/09/02 13:49
-	20	("3953566" "4634631" "4849284" "4886699" "4996097" "5024871" "5055342" "5103293" "5309629" "5319244" "5358775" "5374469" "5422184" "5506049" "5652055" "5656862" "5686191" "5756405" "5858461" "6013588").PN.	USPAT	2004/09/02 13:50
-	2	6518513.URPN.	USPAT	2004/09/02 13:51
-	4	("5342207" "5601678" "6163957" "6326555").PN.	USPAT	2004/09/02 13:52
-	0	6570098.URPN.	USPAT	2004/09/02 13:53
-	554977	(via near hole) or (through near hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/09/02 14:32
-	2239	((via near hole) or (through near hole)) near10 bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/09/02 15:30
-	835	((via near hole) or (through near hole)) near10 bump) and (circuit near board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/09/02 14:33
-	599	((via near hole) or (through near hole)) near10 bump) same (resin or adhesive or glue)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/09/02 14:33
-	82	((via near hole) or (through near hole)) near10 bump) same (resin or adhesive or glue)) same (circuit near board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/09/02 14:51
-	973	((via near hole) or (through near hole)) near10 bump	EPO; JPO; DERWENT; IBM_TDB	2004/09/02 14:51

-	241	((via near hole) or (through near hole)) near10 bump) and ((circuit near board) or multilayer or (multi near layer))	EPO; JPO; DERWENT; IBM_TDB	2004/09/02 14:52
-	294	((via near hole) or (through near hole)) near10 ((conductive or conductor or electrode) near bump)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/02 15:31